LM35 Precision Centigrade Temperature Sensors

1 Features

- Calibrated Directly in Celsius (Centigrade)
- Linear + 10-mV/°C Scale Factor
- 0.5°C Ensured Accuracy (at 25°C)
- Rated for Full −55°C to 150°C Range
- Suitable for Remote Applications
- Low-Cost Due to Wafer-Level Trimming
- Operates from 4 V to 30 V
- Less than 60-μA Current Drain
- Low Self-Heating, 0.08°C in Still Air
- Non-Linearity Only ±¼°C Typical
- Low-Impedance Output, 0.1 Ω for 1-mA Load

2 Applications

- Power Supplies
- Battery Management
- HVAC
- Appliances

3 Description

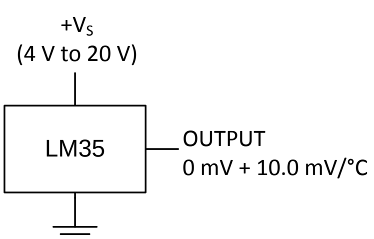
The LM35 series are precision integrated-circuit temperature devices with an output voltage linearly-proportional to the Centigrade temperature. The LM35 device has an advantage over linear temperature sensors calibrated in Kelvin, as the user is not required to subtract a large constant voltage from the output to obtain convenient Centigrade scaling. The LM35 device does not require any external calibration or trimming to provide typical accuracies of ±¼°C at room temperature and ±¾°C over a full −55°C to 150°C temperature range. Lower cost is assured by trimming and calibration at the wafer level. The low-output impedance, linear output, and precise inherent calibration of the LM35 device makes interfacing to readout or control circuitry especially easy. The device is used with single power supplies, or with plus and minus supplies. As the LM35 device draws only 60 μA from the supply, it has very low self-heating of less than 0.1°C in still air. The LM35 device is rated to operate over a −55°C to 150°C temperature range, while the LM35C device is rated for a −40°C to 110°C range (−10° with improved accuracy). The LM35-series devices are available packaged in hermetic TO transistor packages, while the LM35C, LM35CA, and LM35D devices are available in the plastic TO-92 transistor package. The LM35D device is available in an 8-lead surface-mount small-outline package and a plastic TO-220 package.

Device Information[(1)]

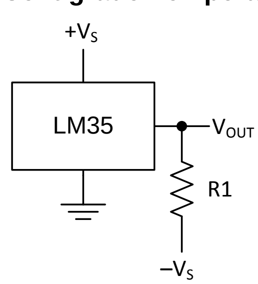
PART NUMBER	PACKAGE	BODY SIZE (NOM)
LM35	TO-CAN (3)	4.699 mm × 4.699 mm
	TO-92 (3)	4.30 mm × 4.30 mm
	SOIC (8)	4.90 mm × 3.91 mm
	TO-220 (3)	14.986 mm × 10.16 mm

(1) For all available packages, see the orderable addendum at the end of the datasheet.

Basic Centigrade Temperature Sensor (2°C to 150°C)



Full-Range Centigrade Temperature Sensor



Choose $R_1 = –V_S$ / 50 µA
V_{OUT} = 1500 mV at 150°C
V_{OUT} = 250 mV at 25°C
V_{OUT} = –550 mV at –55°C

An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

Table of Contents

1 Features 1
2 Applications 1
3 Description 1
4 Revision History 2
5 Pin Configuration and Functions 3
6 Specifications 4
6.1 Absolute Maximum Ratings 4
6.2 ESD Ratings 4
6.3 Recommended Operating Conditions 4
6.4 Thermal Information 4
6.5 Electrical Characteristics: LM35A, LM35CA Limits 5
6.6 Electrical Characteristics: LM35A, LM35CA 6
6.7 Electrical Characteristics: LM35, LM35C, LM35D Limits 8
6.8 Electrical Characteristics: LM35, LM35C, LM35D 9
6.9 Typical Characteristics 11
7 Detailed Description 13
7.1 Overview 13
7.2 Functional Block Diagram 13
7.3 Feature Description 13
7.4 Device Functional Modes 13
8 Application and Implementation 14
8.1 Application Information 14
8.2 Typical Application 15
8.3 System Examples 16
9 Power Supply Recommendations 19
10 Layout 19
10.1 Layout Guidelines 19
10.2 Layout Example 20
11 Device and Documentation Support 21
11.1 Trademarks 21
11.2 Electrostatic Discharge Caution 21
11.3 Glossary 21
12 Mechanical, Packaging, and Orderable Information 21

4 Revision History

Changes from Revision F (January 2016) to Revision G **Page**

- Equation 1, changed From: 10 mV/°F To: 10mv/°C 13
- *Power Supply Recommendations*, changed From: "4-V to 5.5-V power supply" To: "4-V to 30-V power supply: 19

Changes from Revision E (January 2015) to Revision F **Page**

- Changed NDV Package (TO-CAN) pinout from Top View to Bottom View 3

Changes from Revision D (October 2013) to Revision E **Page**

- Added *Pin Configuration and Functions* section, *ESD Ratings* table, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section 1

Changes from Revision C (July 2013) to Revision D **Page**

- Changed *W* to *Ω* 1
- Changed *W* to *Ω* in *Abs Max* tablenote. 4

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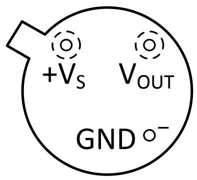
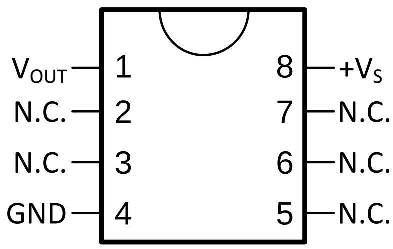
5 Pin Configuration and Functions

NDV Package
3-Pin TO-CAN
(Bottom View)



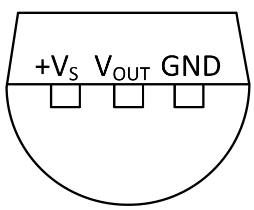
Case is connected to negative pin (GND)

D Package
8-PIN SOIC
(Top View)

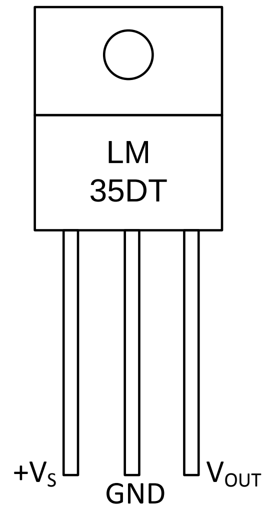


N.C. = No connection

LP Package
3-Pin TO-92
(Bottom View)



NEB Package
3-Pin TO-220
(Top View)



Tab is connected to the negative pin (GND).

NOTE: The LM35DT pinout is different than the discontinued LM35DP

Pin Functions

PIN					TYPE	DESCRIPTION
NAME	TO46	TO92	TO220	SO8		
V$_{OUT}$	—	—	—	1	O	Temperature Sensor Analog Output
N.C.	—	—	—	2	—	No Connection
	—	—	—	3		
GND	—	—	—	4	GROUND	Device ground pin, connect to power supply negative terminal
N.C.	—	—	—	5	—	No Connection
	—	—	—	6		
	—	—	—	7		
+V$_S$	—	—	—	8	POWER	Positive power supply pin

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)[1][2]

		MIN	MAX	UNIT
Supply voltage		–0.2	35	V
Output voltage		–1	6	V
Output current			10	mA
Maximum Junction Temperature, $T_J$max			150	°C
Storage Temperature, T_{stg}	TO-CAN, TO-92 Package	–60	150	°C
	TO-220, SOIC Package	–65	150	

(1) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.
(2) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. DC and AC electrical specifications do not apply when operating the device beyond its rated operating conditions.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001[1]	±2500	V

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
Specified operating temperature: T_{MIN} to T_{MAX}	LM35, LM35A	–55	150	°C
	LM35C, LM35CA	–40	110	
	LM35D	0	100	
Supply Voltage ($+V_S$)		4	30	V

6.4 Thermal Information

THERMAL METRIC[1][2]		LM35				UNIT
		NDV	LP	D	NEB	
		3 PINS		8 PINS	3 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	400	180	220	90	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	24	—	—	—	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, SPRA953.
(2) For additional thermal resistance information, see *Typical Application*.

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6.5 Electrical Characteristics: LM35A, LM35CA Limits

Unless otherwise noted, these specifications apply: −55°C ≤ T_J ≤ 150°C for the LM35 and LM35A; −40°C ≤ T_J ≤ 110°C for the LM35C and LM35CA; and 0°C ≤ T_J ≤ 100°C for the LM35D. V_S = 5 Vdc and I_{LOAD} = 50 µA, in the circuit of Full-Range Centigrade Temperature Sensor. These specifications also apply from 2°C to T_{MAX} in the circuit of Figure 14.

PARAMETER	TEST CONDITIONS	LM35A			LM35CA			UNIT
		TYP	TESTED LIMIT[1]	DESIGN LIMIT[2]	TYP	TESTED LIMIT[1]	DESIGN LIMIT[2]	
Accuracy[3]	T_A = 25°C	±0.2	±0.5		±0.2	±0.5		°C
	T_A = –10°C	±0.3			±0.3		±1	
	$T_A = T_{MAX}$	±0.4	±1		±0.4	±1		
	$T_A = T_{MIN}$	±0.4	±1		±0.4		±1.5	
Nonlinearity[4]	$T_{MIN} \le T_A \le T_{MAX}$, –40°C ≤ T_J ≤ 125°C	±0.18		±0.35	±0.15		±0.3	°C
Sensor gain (average slope)	$T_{MIN} \le T_A \le T_{MAX}$	10	9.9		10		9.9	mV/°C
	–40°C ≤ T_J ≤ 125°C	10	10.1		10		10.1	
Load regulation[5] 0 ≤ I_L ≤ 1 mA	T_A = 25°C	±0.4	±1		±0.4	±1		mV/mA
	$T_{MIN} \le T_A \le T_{MAX}$, –40°C ≤ T_J ≤ 125°C	±0.5		±3	±0.5		±3	
Line regulation[5]	T_A = 25°C	±0.01	±0.05		±0.01	±0.05		mV/V
	4 V ≤ V_S ≤ 30 V, –40°C ≤ T_J ≤ 125°C	±0.02		±0.1	±0.02		±0.1	
Quiescent current[6]	V_S = 5 V, 25°C	56	67		56	67		µA
	V_S = 5 V, –40°C ≤ T_J ≤ 125°C	105		131	91		114	
	V_S = 30 V, 25°C	56.2	68		56.2	68		
	V_S = 30 V, –40°C ≤ T_J ≤ 125°C	105.5		133	91.5		116	
Change of quiescent current[5]	4 V ≤ V_S ≤ 30 V, 25°C	0.2	1		0.2	1		µA
	4 V ≤ V_S ≤ 30 V, –40°C ≤ T_J ≤ 125°C	0.5		2	0.5		2	
Temperature coefficient of quiescent current	–40°C ≤ T_J ≤ 125°C	0.39		0.5	0.39		0.5	µA/°C
Minimum temperature for rate accuracy	In circuit of Figure 14, I_L = 0	1.5		2	1.5		2	°C
Long term stability	$T_J = T_{MAX}$, for 1000 hours	±0.08			±0.08			°C

(1) Tested Limits are ensured and 100% tested in production.
(2) Design Limits are ensured (but not 100% production tested) over the indicated temperature and supply voltage ranges. These limits are not used to calculate outgoing quality levels.
(3) Accuracy is defined as the error between the output voltage and 10 mv/°C times the case temperature of the device, at specified conditions of voltage, current, and temperature (expressed in °C).
(4) Non-linearity is defined as the deviation of the output-voltage-versus-temperature curve from the best-fit straight line, over the rated temperature range of the device.
(5) Regulation is measured at constant junction temperature, using pulse testing with a low duty cycle. Changes in output due to heating effects can be computed by multiplying the internal dissipation by the thermal resistance.
(6) Quiescent current is defined in the circuit of Figure 14.

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6.6 Electrical Characteristics: LM35A, LM35CA

Unless otherwise noted, these specifications apply: −55°C ≤ T_J ≤ 150°C for the LM35 and LM35A; −40°C ≤ T_J ≤ 110°C for the LM35C and LM35CA; and 0°C ≤ T_J ≤ 100°C for the LM35D. V_S = 5 Vdc and I_{LOAD} = 50 μA, in the circuit of Full-Range Centigrade Temperature Sensor. These specifications also apply from 2°C to T_{MAX} in the circuit of Figure 14.

PARAMETER	TEST CONDITIONS		LM35A			LM35CA			UNIT
			MIN	TYP	MAX	TYP	TYP	MAX	
Accuracy[1]	T_A = 25°C			±0.2			±0.2		°C
		Tested Limit[2]			±0.5			±0.5	
		Design Limit[3]							
	T_A = –10°C			±0.3			±0.3		
		Tested Limit[2]							
		Design Limit[3]						±1	
	$T_A = T_{MAX}$			±0.4			±0.4		
		Tested Limit[2]			±1			±1	
		Design Limit[3]							
	$T_A = T_{MIN}$			±0.4			±0.4		
		Tested Limit[2]			±1				
		Design Limit[3]						±1.5	
Nonlinearity[4]	$T_{MIN} \le T_A \le T_{MAX}$, –40°C ≤ T_J ≤ 125°C			±0.18			±0.15		°C
		Tested Limit[2]							
		Design Limit[3]			±0.35			±0.3	
Sensor gain (average slope)	$T_{MIN} \le T_A \le T_{MAX}$			10			10		mV/°C
		Tested Limit[2]			9.9				
		Design Limit[3]						9.9	
	–40°C ≤ T_J ≤ 125°C			10			10		
		Tested Limit[2]			10.1				
		Design Limit[3]						10.1	
Load regulation[5] 0 ≤ I_L ≤ 1 mA	T_A = 25°C			±0.4			±0.4		mV/mA
		Tested Limit[2]			±1			±1	
		Design Limit[3]							
	$T_{MIN} \le T_A \le T_{MAX}$, –40°C ≤ T_J ≤ 125°C			±0.5			±0.5		
		Tested Limit[2]							
		Design Limit[3]			±3			±3	
Line regulation[5]	T_A = 25°C			±0.01			±0.01		mV/V
		Tested Limit[2]			±0.05			±0.05	
		Design Limit[3]							
	4 V ≤ V_S ≤ 30 V, –40°C ≤ T_J ≤ 125°C			±0.02			±0.02		
		Tested Limit[2]							
		Design Limit[3]			±0.1			±0.1	

(1) Accuracy is defined as the error between the output voltage and 10 mv/°C times the case temperature of the device, at specified conditions of voltage, current, and temperature (expressed in °C).
(2) Tested Limits are ensured and 100% tested in production.
(3) Design Limits are ensured (but not 100% production tested) over the indicated temperature and supply voltage ranges. These limits are not used to calculate outgoing quality levels.
(4) Non-linearity is defined as the deviation of the output-voltage-versus-temperature curve from the best-fit straight line, over the rated temperature range of the device.
(5) Regulation is measured at constant junction temperature, using pulse testing with a low duty cycle. Changes in output due to heating effects can be computed by multiplying the internal dissipation by the thermal resistance.

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Electrical Characteristics: LM35A, LM35CA (continued)

Unless otherwise noted, these specifications apply: −55°C ≤ T_J ≤ 150°C for the LM35 and LM35A; −40°C ≤ T_J ≤ 110°C for the LM35C and LM35CA; and 0°C ≤ T_J ≤ 100°C for the LM35D. V_S = 5 Vdc and I_{LOAD} = 50 μA, in the circuit of Full-Range Centigrade Temperature Sensor. These specifications also apply from 2°C to T_{MAX} in the circuit of Figure 14.

PARAMETER	TEST CONDITIONS		LM35A			LM35CA			UNIT
			MIN	TYP	MAX	TYP	TYP	MAX	
Quiescent current(6)	V_S = 5 V, 25°C			56			56		μA
		Tested Limit(2)			67			67	
		Design Limit(3)							
	V_S = 5 V, –40°C ≤ T_J ≤ 125°C			105			91		
		Tested Limit(2)							
		Design Limit(3)			131			114	
	V_S = 30 V, 25°C			56.2			56.2		
		Tested Limit(2)			68			68	
		Design Limit(3)							
	V_S = 30 V, –40°C ≤ T_J ≤ 125°C			105.5			91.5		
		Tested Limit(2)							
		Design Limit(3)			133			116	
Change of quiescent current(5)	4 V ≤ V_S ≤ 30 V, 25°C			0.2			0.2		μA
		Tested Limit(2)			1			1	
		Design Limit(3)							
	4 V ≤ V_S ≤ 30 V, –40°C ≤ T_J ≤ 125°C			0.5			0.5		
		Tested Limit(2)							
		Design Limit(3)			2			2	
Temperature coefficient of quiescent current	–40°C ≤ T_J ≤ 125°C			0.39			0.39		μA/°C
		Tested Limit(2)							
		Design Limit(3)			0.5			0.5	
Minimum temperature for rate accuracy	In circuit of Figure 14, I_L = 0			1.5			1.5		°C
		Tested Limit(2)							
		Design Limit(3)			2			2	
Long term stability	T_J = T_{MAX}, for 1000 hours			±0.08			±0.08		°C

(6) Quiescent current is defined in the circuit of Figure 14.

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6.7 Electrical Characteristics: LM35, LM35C, LM35D Limits

Unless otherwise noted, these specifications apply: −55°C ≤ T_J ≤ 150°C for the LM35 and LM35A; −40°C ≤ T_J ≤ 110°C for the LM35C and LM35CA; and 0°C ≤ T_J ≤ 100°C for the LM35D. V_S = 5 Vdc and I_{LOAD} = 50 µA, in the circuit of Full-Range Centigrade Temperature Sensor. These specifications also apply from 2°C to T_{MAX} in the circuit of Figure 14.

PARAMETER	TEST CONDITIONS	LM35			LM35C, LM35D			UNIT
		TYP	TESTED LIMIT (1)	DESIGN LIMIT (2)	TYP	TESTED LIMIT (1)	DESIGN LIMIT (2)	
Accuracy, LM35, LM35C (3)	T_A = 25°C	±0.4	±1		±0.4	±1		°C
	T_A = –10°C	±0.5			±0.5		±1.5	
	$T_A = T_{MAX}$	±0.8	±1.5		±0.8		±1.5	
	$T_A = T_{MIN}$	±0.8		±1.5	±0.8		±2	
Accuracy, LM35D (3)	T_A = 25°C				±0.6	±1.5		°C
	$T_A = T_{MAX}$				±0.9		±2	
	$T_A = T_{MIN}$				±0.9		±2	
Nonlinearity (4)	$T_{MIN} \le T_A \le T_{MAX}$, –40°C ≤ T_J ≤ 125°C	±0.3		±0.5	±0.2		±0.5	°C
Sensor gain (average slope)	$T_{MIN} \le T_A \le T_{MAX}$, –40°C ≤ T_J ≤ 125°C	10	9.8		10		9.8	mV/°C
		10	10.2		10		10.2	
Load regulation (5) 0 ≤ I_L ≤ 1 mA	T_A = 25°C	±0.4	±2		±0.4	±2		mV/mA
	$T_{MIN} \le T_A \le T_{MAX}$, –40°C ≤ T_J ≤ 125°C	±0.5		±5	±0.5		±5	
Line regulation (5)	T_A = 25°C	±0.01	±0.1		±0.01	±0.1		mV/V
	4 V ≤ V_S ≤ 30 V, –40°C ≤ T_J ≤ 125°C	±0.02		±0.2	±0.02		±0.2	
Quiescent current (6)	V_S = 5 V, 25°C	56	80		56	80		µA
	V_S = 5 V, –40°C ≤ T_J ≤ 125°C	105		158	91		138	
	V_S = 30 V, 25°C	56.2	82		56.2	82		
	V_S = 30 V, –40°C ≤ T_J ≤ 125°C	105.5		161	91.5		141	
Change of quiescent current (5)	4 V ≤ V_S ≤ 30 V, 25°C	0.2	2		0.2	2		µA
	4 V ≤ V_S ≤ 30 V, –40°C ≤ T_J ≤ 125°C	0.5		3	0.5		**3**	
Temperature coefficient of quiescent current	–40°C ≤ T_J ≤ 125°C	0.39		0.7	0.39		0.7	µA/°C
Minimum temperature for rate accuracy	In circuit of Figure 14, I_L = 0	1.5		2	1.5		2	°C
Long term stability	$T_J = T_{MAX}$, for 1000 hours	±0.08			±0.08			°C

(1) Tested Limits are ensured and 100% tested in production.
(2) Design Limits are ensured (but not 100% production tested) over the indicated temperature and supply voltage ranges. These limits are not used to calculate outgoing quality levels.
(3) Accuracy is defined as the error between the output voltage and 10 mv/°C times the case temperature of the device, at specified conditions of voltage, current, and temperature (expressed in °C).
(4) Non-linearity is defined as the deviation of the output-voltage-versus-temperature curve from the best-fit straight line, over the rated temperature range of the device.
(5) Regulation is measured at constant junction temperature, using pulse testing with a low duty cycle. Changes in output due to heating effects can be computed by multiplying the internal dissipation by the thermal resistance.
(6) Quiescent current is defined in the circuit of Figure 14.

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6.8 Electrical Characteristics: LM35, LM35C, LM35D

Unless otherwise noted, these specifications apply: −55°C ≤ T_J ≤ 150°C for the LM35 and LM35A; −40°C ≤ T_J ≤ 110°C for the LM35C and LM35CA; and 0°C ≤ T_J ≤ 100°C for the LM35D. V_S = 5 Vdc and I_{LOAD} = 50 μA, in the circuit of Full-Range Centigrade Temperature Sensor. These specifications also apply from 2°C to T_{MAX} in the circuit of Figure 14.

PARAMETER	TEST CONDITIONS		LM35			LM35C, LM35D			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
Accuracy, LM35, LM35C(1)	T_A = 25°C			±0.4			±0.4		°C
		Tested Limit(2)			±1			±1	
		Design Limit(3)							
	T_A = –10°C			±0.5			±0.5		
		Tested Limit(2)							
		Design Limit(3)						±1.5	
	T_A = T_{MAX}			±0.8			±0.8		
		Tested Limit(2)			±1.5				
		Design Limit(3)						±1.5	
	T_A = T_{MIN}			±0.8			±0.8		
		Tested Limit(2)							
		Design Limit(3)			±1.5			±2	
Accuracy, LM35D(1)	T_A = 25°C						±0.6		°C
		Tested Limit(2)						±1.5	
		Design Limit(3)							
	T_A = T_{MAX}						±0.9		
		Tested Limit(2)							
		Design Limit(3)						±2	
	T_A = T_{MIN}						±0.9		
		Tested Limit(2)							
		Design Limit(3)						±2	
Nonlinearity(4)	T_{MIN} ≤ T_A ≤ T_{MAX}, –40°C ≤ T_J ≤ 125°C			±0.3			±0.2		°C
		Tested Limit(2)							
		Design Limit(3)			±0.5			±0.5	
Sensor gain (average slope)	T_{MIN} ≤ T_A ≤ T_{MAX}, –40°C ≤ T_J ≤ 125°C			10			10		mV/°C
		Tested Limit(2)			9.8				
		Design Limit(3)						9.8	
				10			10		
		Tested Limit(2)			10.2				
		Design Limit(3)						10.2	
Load regulation(5) 0 ≤ I_L ≤ 1 mA	T_A = 25°C			±0.4			±0.4		mV/mA
		Tested Limit(2)			±2			±2	
		Design Limit(3)							
	T_{MIN} ≤ T_A ≤ T_{MAX}, –40°C ≤ T_J ≤ 125°C			±0.5			±0.5		
		Tested Limit(2)							
		Design Limit(3)			±5			±5	

(1) Accuracy is defined as the error between the output voltage and 10 mv/°C times the case temperature of the device, at specified conditions of voltage, current, and temperature (expressed in °C).
(2) Tested Limits are ensured and 100% tested in production.
(3) Design Limits are ensured (but not 100% production tested) over the indicated temperature and supply voltage ranges. These limits are not used to calculate outgoing quality levels.
(4) Non-linearity is defined as the deviation of the output-voltage-versus-temperature curve from the best-fit straight line, over the rated temperature range of the device.
(5) Regulation is measured at constant junction temperature, using pulse testing with a low duty cycle. Changes in output due to heating effects can be computed by multiplying the internal dissipation by the thermal resistance.

Electrical Characteristics: LM35, LM35C, LM35D (continued)

Unless otherwise noted, these specifications apply: −55°C ≤ T_J ≤ 150°C for the LM35 and LM35A; −40°C ≤ T_J ≤ 110°C for the LM35C and LM35CA; and 0°C ≤ T_J ≤ 100°C for the LM35D. V_S = 5 Vdc and I_{LOAD} = 50 µA, in the circuit of Full-Range Centigrade Temperature Sensor. These specifications also apply from 2°C to T_{MAX} in the circuit of Figure 14.

PARAMETER	TEST CONDITIONS		LM35 MIN	LM35 TYP	LM35 MAX	LM35C, LM35D MIN	LM35C, LM35D TYP	LM35C, LM35D MAX	UNIT
Line regulation[5]	T_A = 25°C			±0.01			±0.01		mV/V
		Tested Limit[2]			±0.1				
		Design Limit[3]						±0.1	
	4 V ≤ V_S ≤ 30 V, –40°C ≤ T_J ≤ 125°C			±0.02			±0.02		
		Tested Limit[2]							
		Design Limit[3]			±0.2			±0.2	
Quiescent current[6]	V_S = 5 V, 25°C			56			56		µA
		Tested Limit[2]			80			80	
		Design Limit[3]							
	V_S = 5 V, –40°C ≤ T_J ≤ 125°C			105			91		
		Tested Limit[2]							
		Design Limit[3]			158			138	
	V_S = 30 V, 25°C			56.2			56.2		
		Tested Limit[2]			82			82	
		Design Limit[3]							
	V_S = 30 V, –40°C ≤ T_J ≤ 125°C			105.5			91.5		
		Tested Limit[2]							
		Design Limit[3]			161			141	
Change of quiescent current[5]	4 V ≤ V_S ≤ 30 V, 25°C			0.2			0.2		µA
		Tested Limit[2]						2	
		Design Limit[3]			2				
	4 V ≤ V_S ≤ 30 V, –40°C ≤ T_J ≤ 125°C			0.5			0.5		
		Tested Limit[2]							
		Design Limit[3]			3			3	
Temperature coefficient of quiescent current	–40°C ≤ T_J ≤ 125°C			0.39			0.39		µA/°C
		Tested Limit[2]							
		Design Limit[3]			0.7			0.7	
Minimum temperature for rate accuracy	In circuit of Figure 14, I_L = 0			1.5			1.5		°C
		Tested Limit[2]							
		Design Limit[3]			2			2	
Long term stability	T_J = T_{MAX}, for 1000 hours			±0.08			±0.08		°C

(6) Quiescent current is defined in the circuit of Figure 14.

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6.9 Typical Characteristics

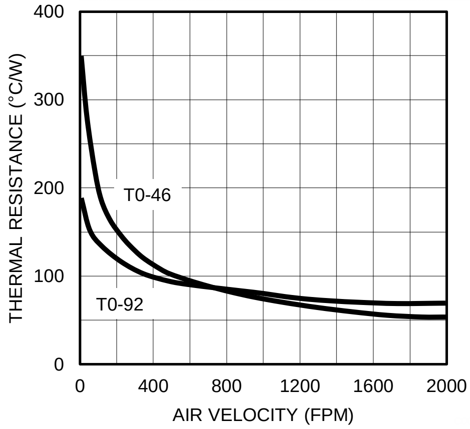

Figure 1. Thermal Resistance Junction To Air

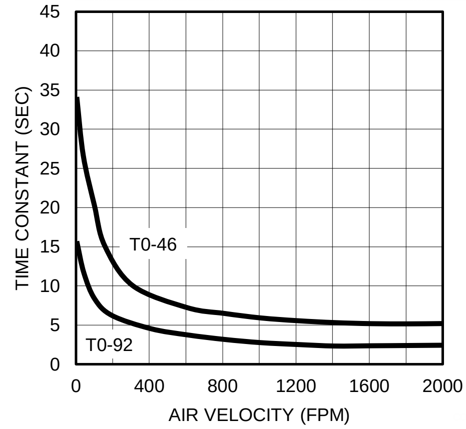

Figure 2. Thermal Time Constant

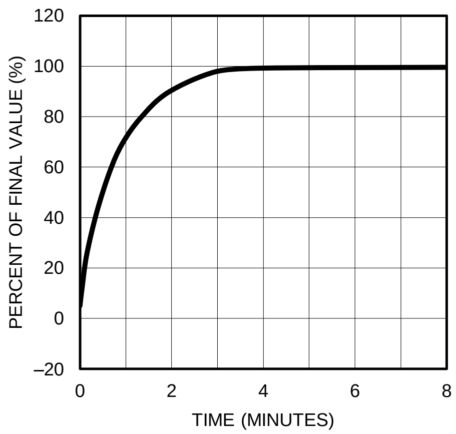

Figure 3. Thermal Response In Still Air

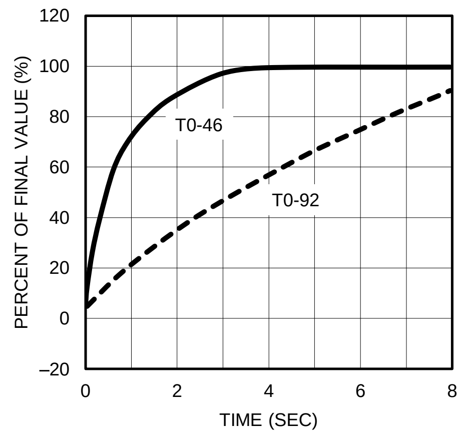

Figure 4. Thermal Response In Stirred Oil Bath

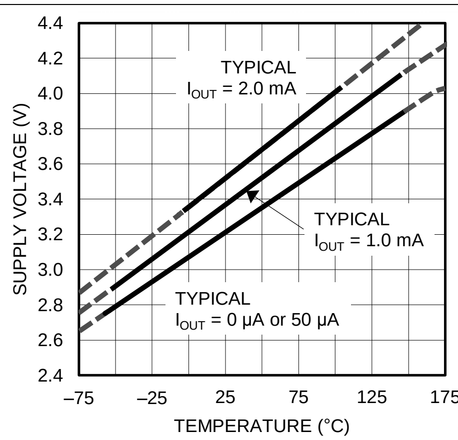

Figure 5. Minimum Supply Voltage vs Temperature

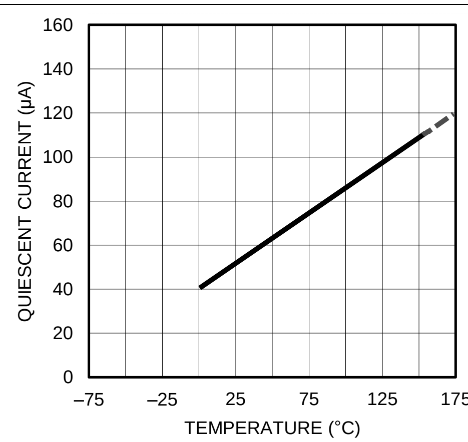

Figure 6. Quiescent Current vs Temperature (in Circuit of Figure 14)

Typical Characteristics (continued)

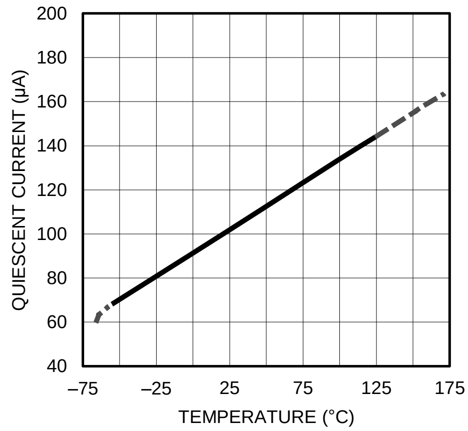

Figure 7. Quiescent Current vs Temperature (in Circuit of Full-Range Centigrade Temperature Sensor)

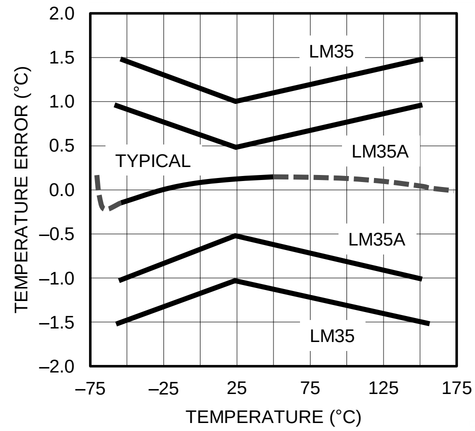

Figure 8. Accuracy vs Temperature (Ensured)

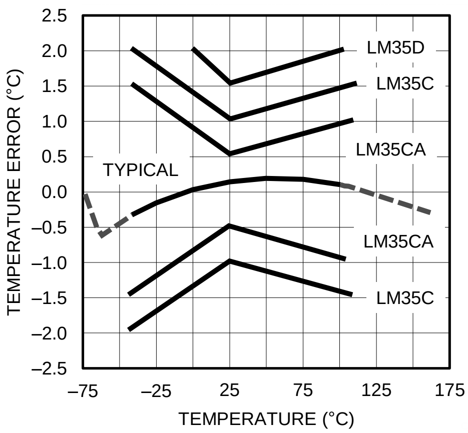

Figure 9. Accuracy vs Temperature (Ensured)

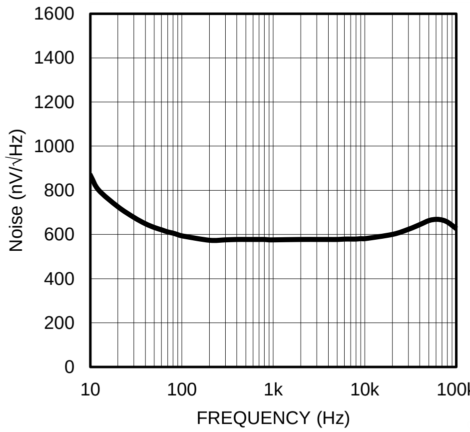

Figure 10. Noise Voltage

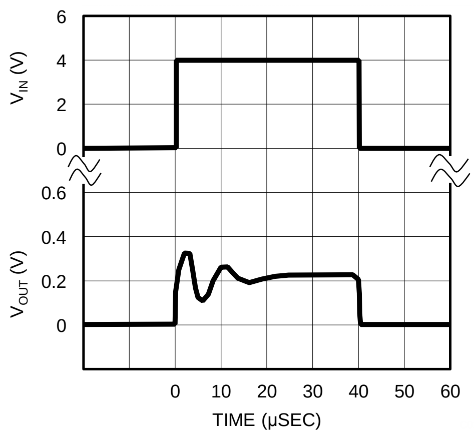

Figure 11. Start-Up Response

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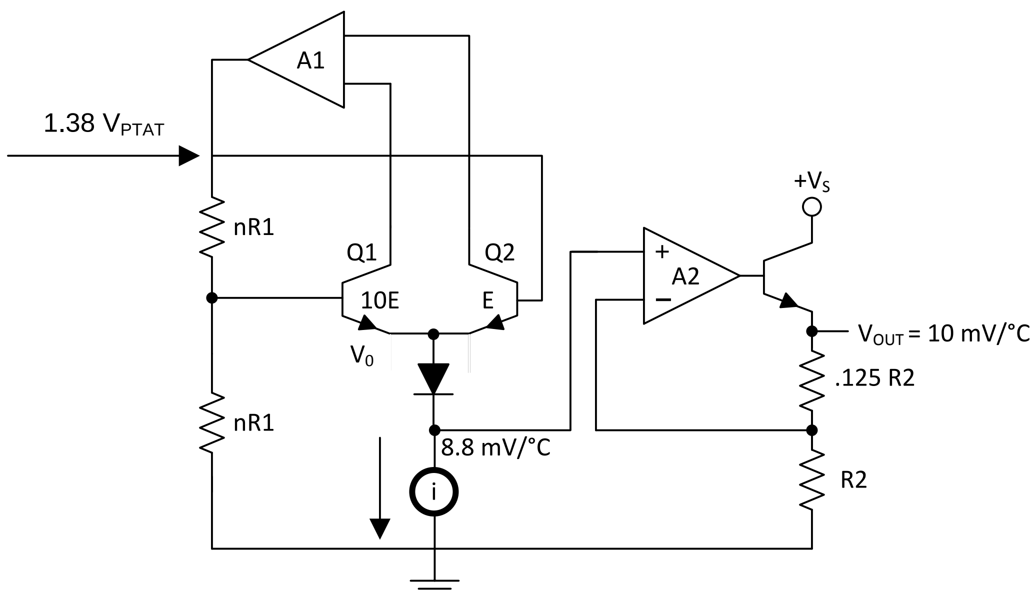
7 Detailed Description

7.1 Overview

The LM35-series devices are precision integrated-circuit temperature sensors, with an output voltage linearly proportional to the Centigrade temperature. The LM35 device has an advantage over linear temperature sensors calibrated in Kelvin, as the user is not required to subtract a large constant voltage from the output to obtain convenient Centigrade scaling. The LM35 device does not require any external calibration or trimming to provide typical accuracies of ± ¼ °C at room temperature and ± ¾ °C over a full −55°C to 150°C temperature range. Lower cost is assured by trimming and calibration at the wafer level. The low output impedance, linear output, and precise inherent calibration of the LM35 device makes interfacing to readout or control circuitry especially easy. The device is used with single power supplies, or with plus and minus supplies. As the LM35 device draws only 60 µA from the supply, it has very low self-heating of less than 0.1°C in still air. The LM35 device is rated to operate over a −55°C to 150°C temperature range, while the LM35C device is rated for a −40°C to 110°C range (−10° with improved accuracy). The temperature-sensing element is comprised of a delta-V BE architecture.

The temperature-sensing element is then buffered by an amplifier and provided to the VOUT pin. The amplifier has a simple class A output stage with typical 0.5-Ω output impedance as shown in the *Functional Block Diagram*. Therefore the LM35 can only source current and it's sinking capability is limited to 1 µA.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 LM35 Transfer Function

The accuracy specifications of the LM35 are given with respect to a simple linear transfer function:

$V_{OUT} = 10\ \text{mv/°C} \times T$

where

- V_{OUT} is the LM35 output voltage
- T is the temperature in °C (1)

7.4 Device Functional Modes

The only functional mode of the LM35 is that it has an analog output directly proportional to temperature.

8 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The features of the LM35 make it suitable for many general temperature sensing applications. Multiple package options expand on it's flexibility.

8.1.1 Capacitive Drive Capability

Like most micropower circuits, the LM35 device has a limited ability to drive heavy capacitive loads. Alone, the LM35 device is able to drive 50 pF without special precautions. If heavier loads are anticipated, isolating or decoupling the load with a resistor is easy (see Figure 12). The tolerance of capacitance can be improved with a series R-C damper from output to ground (see Figure 13).

When the LM35 device is applied with a 200-Ω load resistor as shown in Figure 16, Figure 17, or Figure 19, the device is relatively immune to wiring capacitance because the capacitance forms a bypass from ground to input and not on the output. However, as with any linear circuit connected to wires in a hostile environment, performance is affected adversely by intense electromagnetic sources (such as relays, radio transmitters, motors with arcing brushes, and SCR transients), because the wiring acts as a receiving antenna and the internal junctions act as rectifiers. For best results in such cases, a bypass capacitor from V_{IN} to ground and a series R-C damper, such as 75 Ω in series with 0.2 or 1 μF from output to ground, are often useful. Examples are shown in Figure 13, Figure 24, and Figure 25.

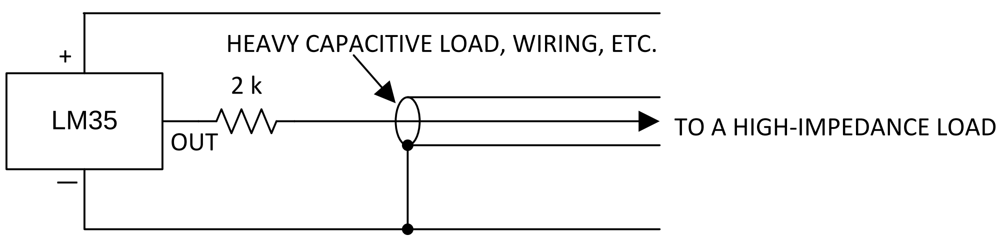


Figure 12. LM35 with Decoupling from Capacitive Load

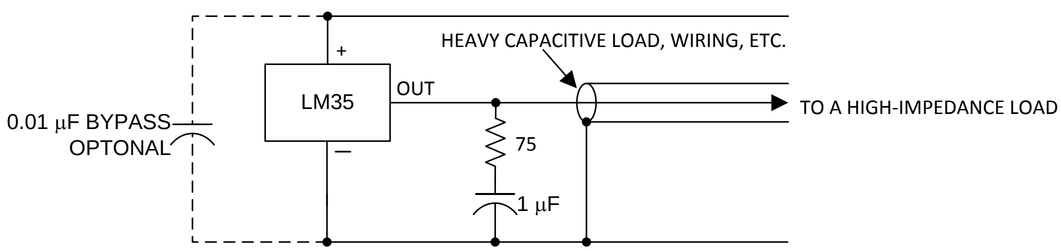


Figure 13. LM35 with R-C Damper

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8.2 Typical Application

8.2.1 Basic Centigrade Temperature Sensor

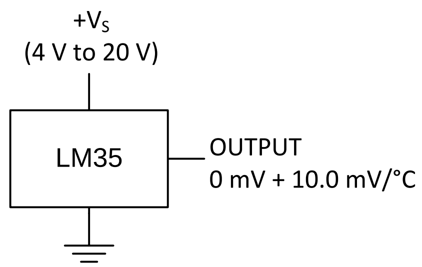

Figure 14. Basic Centigrade Temperature Sensor (2 °C to 150 °C)

8.2.1.1 Design Requirements

Table 1. Design Parameters

PARAMETER	VALUE
Accuracy at 25°C	±0.5°C
Accuracy from –55 °C to 150°C	±1°C
Temperature Slope	10 mV/°C

8.2.1.2 Detailed Design Procedure

Because the LM35 device is a simple temperature sensor that provides an analog output, design requirements related to layout are more important than electrical requirements. For a detailed description, refer to the *Layout*.

8.2.1.3 Application Curve

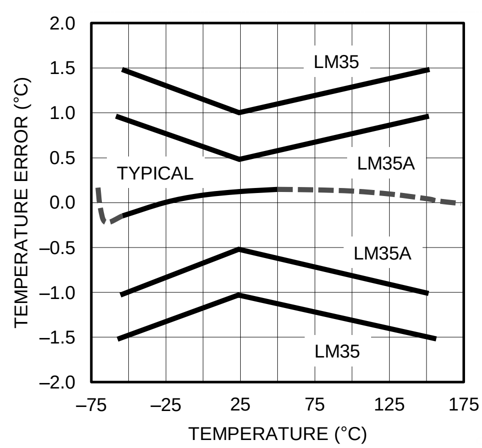

Figure 15. Accuracy vs Temperature (Ensured)

8.3 System Examples

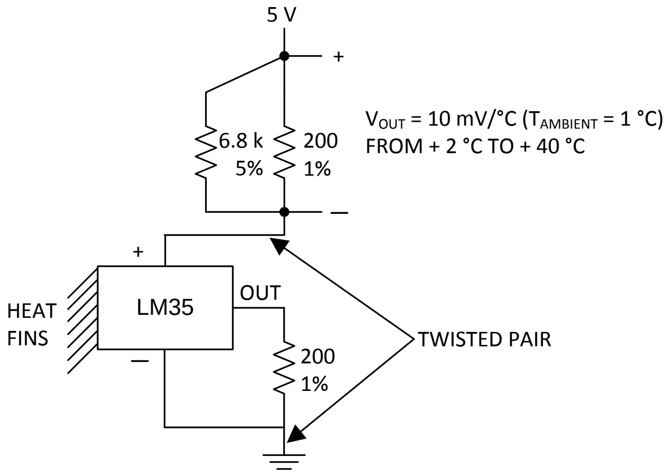

Figure 16. Two-Wire Remote Temperature Sensor (Grounded Sensor)

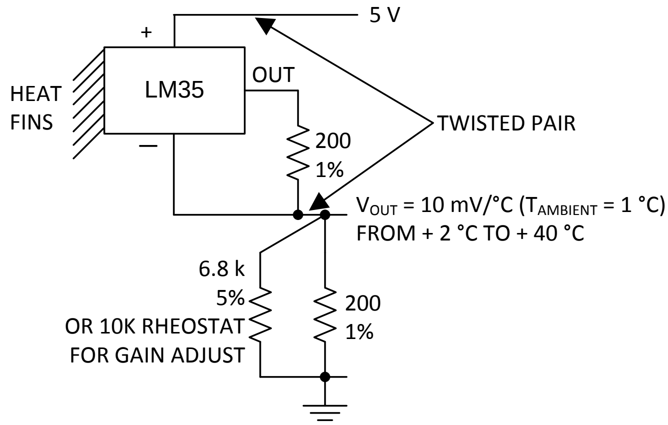

Figure 17. Two-Wire Remote Temperature Sensor (Output Referred to Ground)

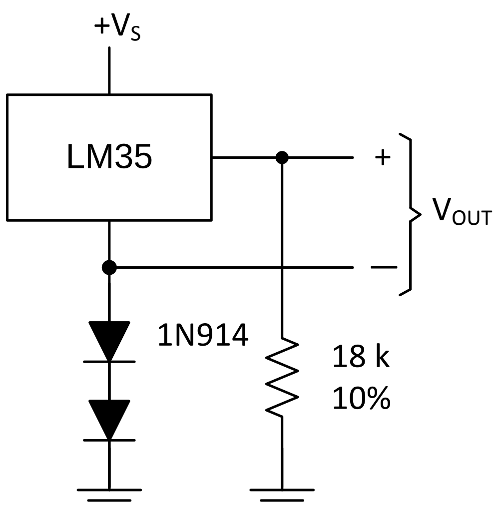

Figure 18. Temperature Sensor, Single Supply (−55° to +150°C)

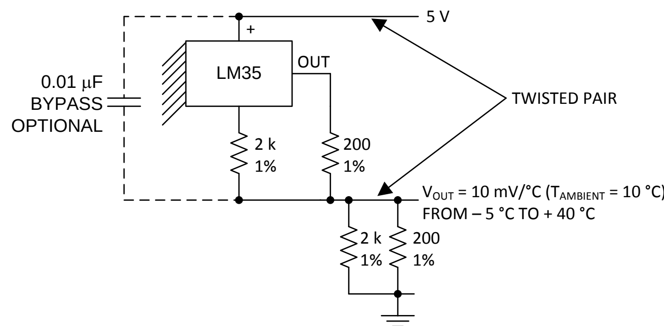

Figure 19. Two-Wire Remote Temperature Sensor (Output Referred to Ground)

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System Examples (continued)

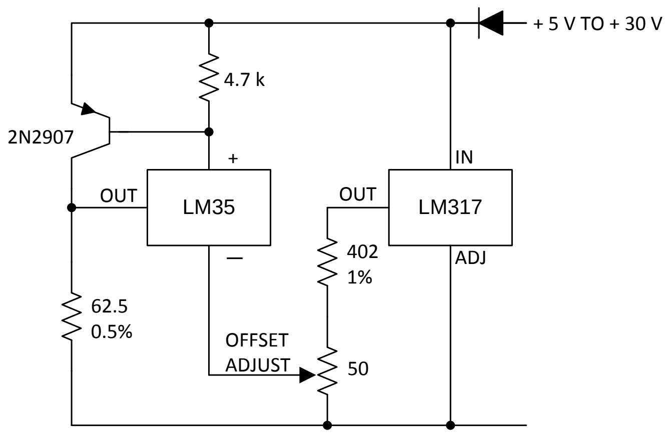


Figure 20. 4-To-20 mA Current Source (0°C to 100°C)

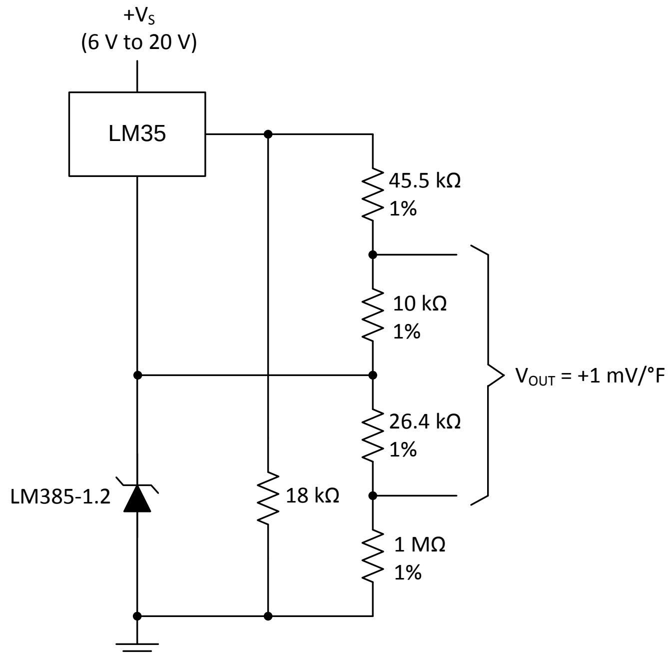


Figure 21. Fahrenheit Thermometer

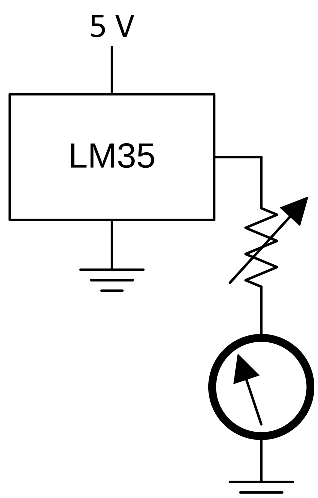


Figure 22. Centigrade Thermometer (Analog Meter)

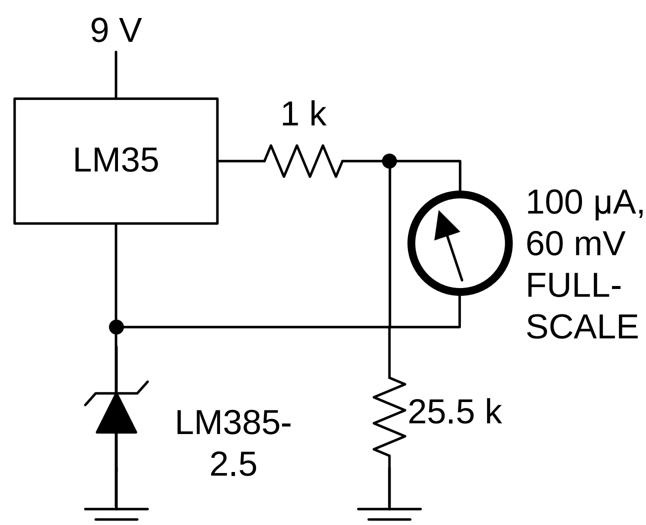


Figure 23. Fahrenheit Thermometer, Expanded Scale Thermometer (50°F to 80°F, for Example Shown)

System Examples (continued)

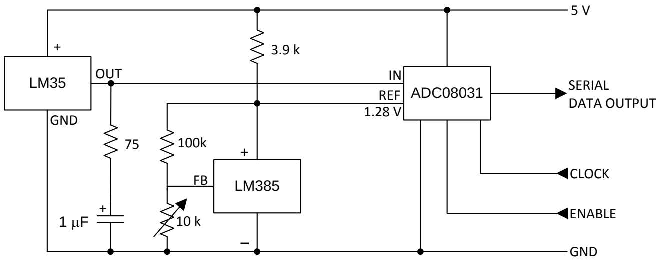


Figure 24. Temperature to Digital Converter (Serial Output) (128°C Full Scale)

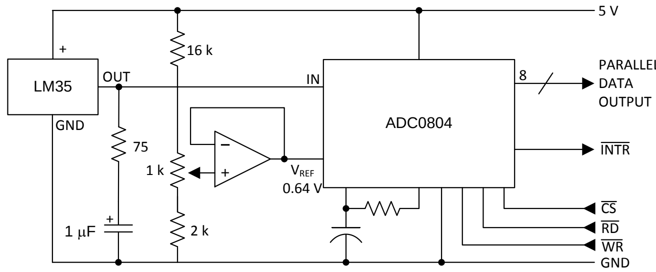
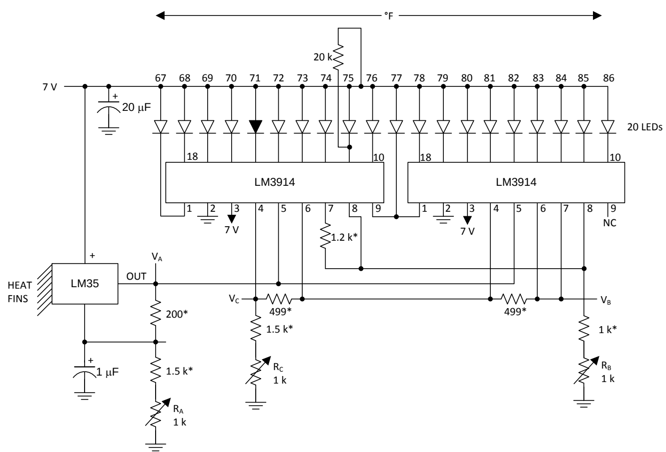


Figure 25. Temperature to Digital Converter (Parallel TRI-STATE Outputs for Standard Data Bus to µP Interface) (128°C Full Scale)



*=1% or 2% film resistor

Trim R_B for V_B = 3.075 V

Trim R_C for V_C = 1.955 V

Trim R_A for V_A = 0.075 V + 100 mV/°C $\times T_{ambient}$

Example, V_A = 2.275 V at 22°C

Figure 26. Bar-Graph Temperature Display (Dot Mode)

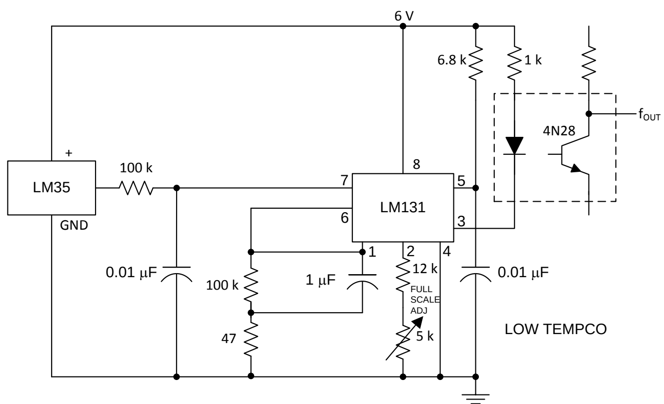


Figure 27. LM35 With Voltage-To-Frequency Converter and Isolated Output (2°C to 150°C; 20 to 1500 Hz)

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9 Power Supply Recommendations

The LM35 device has a very wide 4-V to 30-V power supply voltage range, which makes it ideal for many applications. In noisy environments, TI recommends adding a 0.1 μF from V+ to GND to bypass the power supply voltage. Larger capacitances maybe required and are dependent on the power-supply noise.

10 Layout

10.1 Layout Guidelines

The LM35 is easily applied in the same way as other integrated-circuit temperature sensors. Glue or cement the device to a surface and the temperature should be within about 0.01°C of the surface temperature.

The 0.01°C proximity presumes that the ambient air temperature is almost the same as the surface temperature. If the air temperature were much higher or lower than the surface temperature, the actual temperature of the LM35 die would be at an intermediate temperature between the surface temperature and the air temperature; this is especially true for the TO-92 plastic package. The copper leads in the TO-92 package are the principal thermal path to carry heat into the device, so its temperature might be closer to the air temperature than to the surface temperature.

Ensure that the wiring leaving the LM35 device is held at the same temperature as the surface of interest to minimize the temperature problem. The easiest fix is to cover up these wires with a bead of epoxy. The epoxy bead will ensure that the leads and wires are all at the same temperature as the surface, and that the temperature of the LM35 die is not affected by the air temperature.

The TO-46 metal package can also be soldered to a metal surface or pipe without damage. Of course, in that case the V− terminal of the circuit will be grounded to that metal. Alternatively, mount the LM35 inside a sealed-end metal tube, and then dip into a bath or screw into a threaded hole in a tank. As with any IC, the LM35 device and accompanying wiring and circuits must be kept insulated and dry, to avoid leakage and corrosion. This is especially true if the circuit may operate at cold temperatures where condensation can occur. Printed-circuit coatings and varnishes such as a conformal coating and epoxy paints or dips are often used to insure that moisture cannot corrode the LM35 device or its connections.

These devices are sometimes soldered to a small light-weight heat fin to decrease the thermal time constant and speed up the response in slowly-moving air. On the other hand, a small thermal mass may be added to the sensor, to give the steadiest reading despite small deviations in the air temperature.

Table 2. Temperature Rise of LM35 Due To Self-heating (Thermal Resistance, $R_{\theta JA}$)

	TO, no heat sink	TO(1), small heat fin	TO-92, no heat sink	TO-92(2), small heat fin	SOIC-8, no heat sink	SOIC-8(2), small heat fin	TO-220, no heat sink
Still air	400°C/W	100°C/W	180°C/W	140°C/W	220°C/W	110°C/W	90°C/W
Moving air	100°C/W	40°C/W	90°C/W	70°C/W	105°C/W	90°C/W	26°C/W
Still oil	100°C/W	40°C/W	90°C/W	70°C/W	—	—	—
Stirred oil	50°C/W	30°C/W	45°C/W	40°C/W	—	—	—
(Clamped to metal, Infinite heat sink)	(24°C/W)		—	—	(55°C/W)		—

(1) Wakefield type 201, or 1-in disc of 0.02-in sheet brass, soldered to case, or similar.
(2) TO-92 and SOIC-8 packages glued and leads soldered to 1-in square of 1/16-in printed circuit board with 2-oz foil or similar.

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10.2 Layout Example

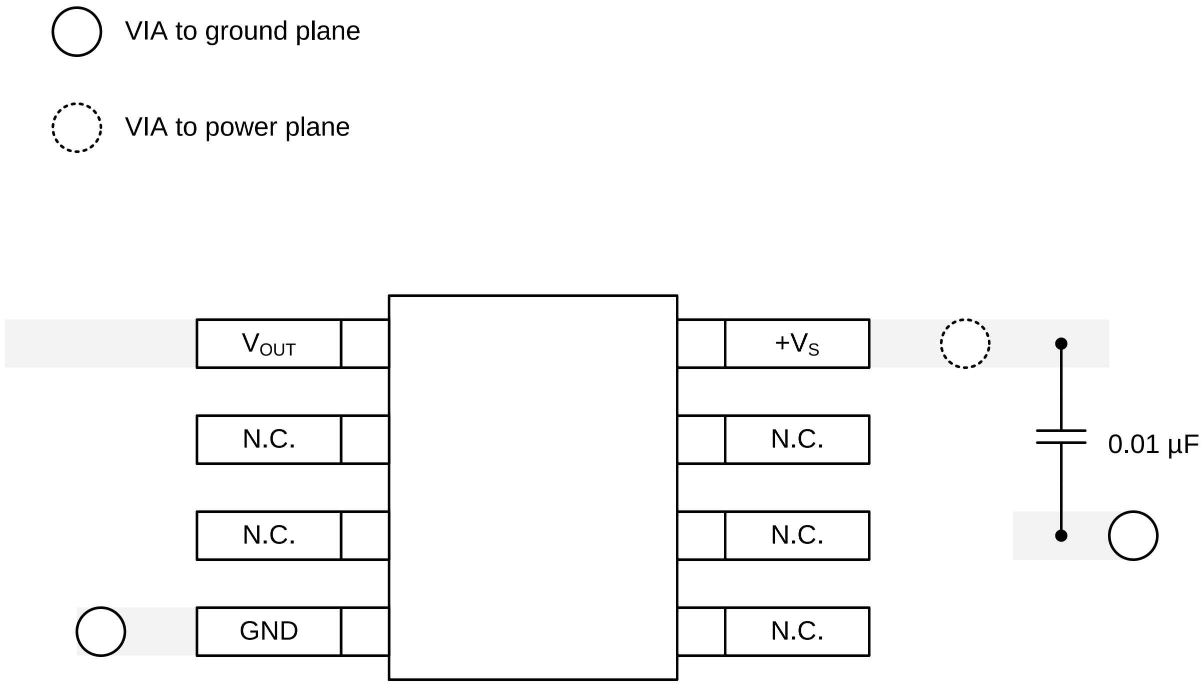

Figure 28. Layout Example

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11 Device and Documentation Support

11.1 Trademarks

All trademarks are the property of their respective owners.

11.2 Electrostatic Discharge Caution

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

11.3 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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